

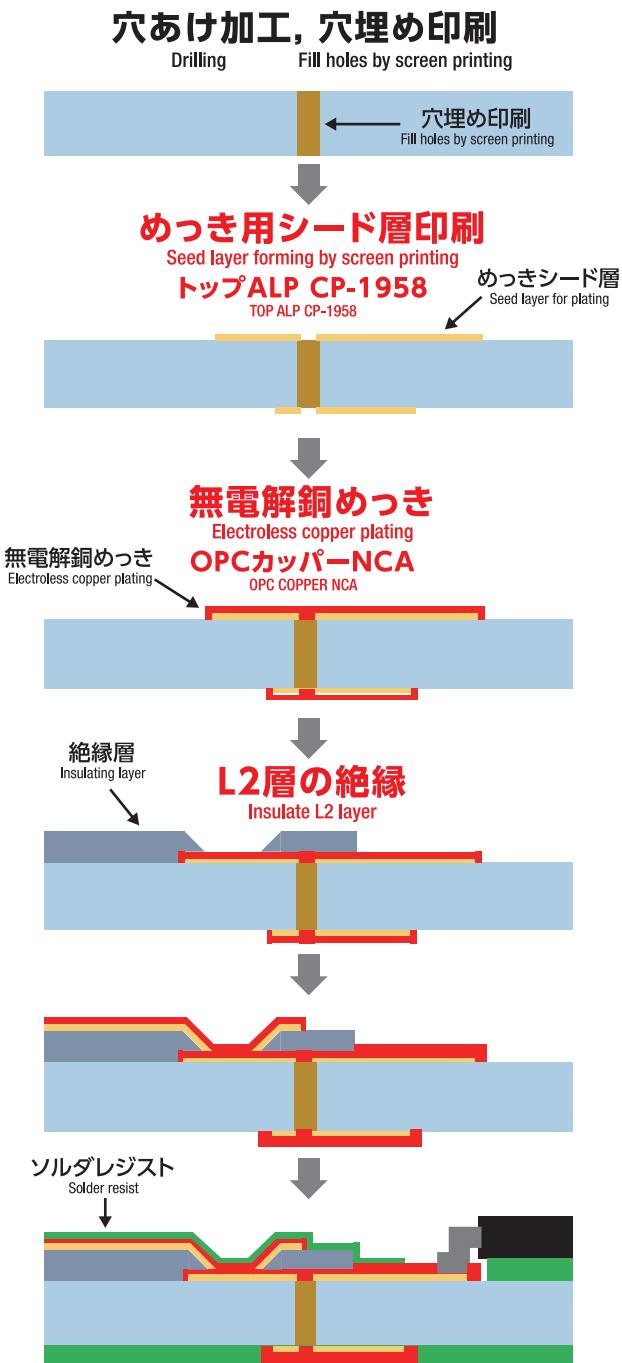
EF-PWB PROCESS

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- スクリーン印刷と無電解銅めっきで回路形成
Can form pattern by screen printing and electroless copper plating
- 既存プロセスと比較し、工程数の削減を実現
Can reduce the number of steps from conventional process
- 多層化対応
Can use for multi-layer PWBS

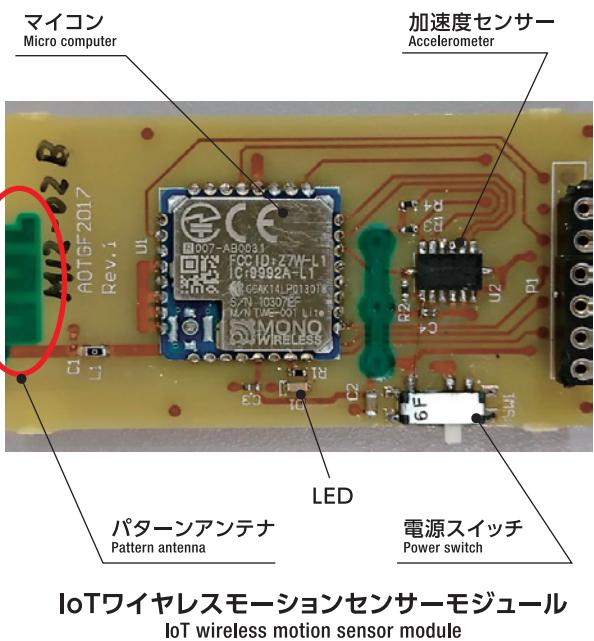
製造プロセス

Process



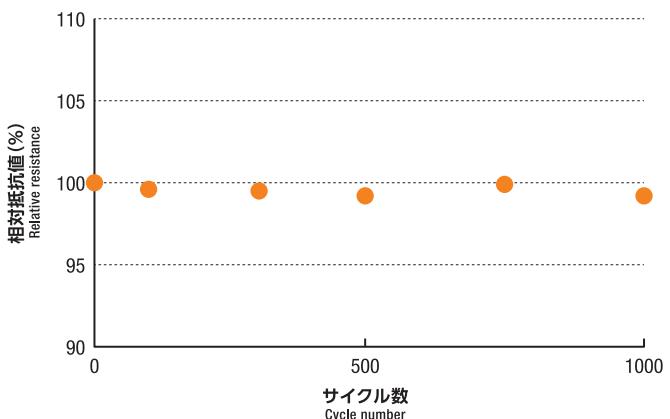
多層基板作製例

Application example to multi-layer PWBS



高い信頼性

High reliability



ヒートサイクル試験における抵抗値変化

Resistance variation in thermo-cycle test

(-65°C 30分 ⇄ 125°C 30分)
30min 30min